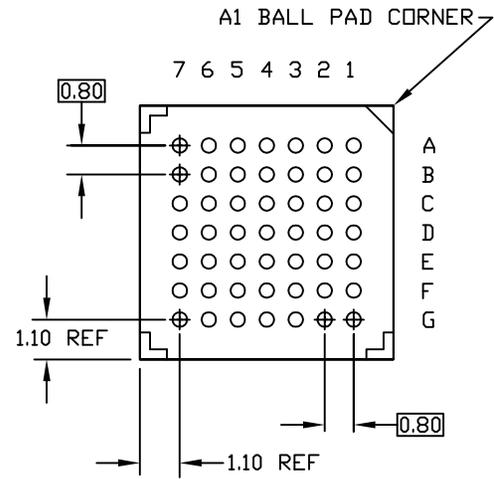
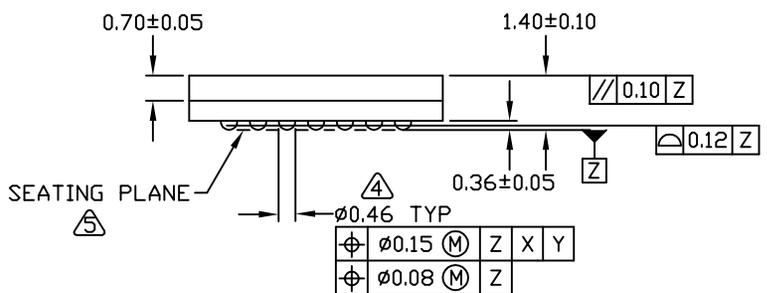


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
3. THE BASIC SOLDER BUMP GRID PITCH IS 0.80
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
5. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. MARKING SHOWN IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
7. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
8. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
9. PACKAGE CODES: X49+/-1, X49+/-3, X4977+/-4

-DRAWING NOT TO SCALE-

<b>MAXIM</b>			
TITLE: PACKAGE OUTLINE, 49 BALLS CSBGA, 7x7x1.4mm, 0.8 mm PITCH, 2 LAYERS			
APPROVAL	DOCUMENT CONTROL NO. 21-0356	REV. C	1/1